

ABSTRACT OF THE DISCLOSURE

Provided is a chemical-amplification positive-working resist composition capable of giving a resist pattern having excellent dry etching resistance and adhesion to the substrate with high pattern resolution and further having a good profile with improvement in the line edge roughness. It is a chemical-amplification positive-working resist composition by using, as the component (A) in a positive-working resist composition comprising (A) a resinous ingredient capable of being imparted with increased solubility in an alkaline aqueous solution by the interaction of an acid, (B) an acid-generating agent ingredient generating an acid by irradiation with a radiation and (C) an organic solvent, a copolymer of which the monomer units constituting the main chain consist of acrylic acid ester or methacrylic acid ester units having solubility-reducing groups, monomer units derived from an ester of acrylic acid or methacrylic acid and a lactone ring-containing bridged saturated polycyclic alcohol and monomer units derived from an ester of acrylic acid or methacrylic acid and a straight-chain alcohol substituted by hydroxyl group, alkoxy group or acyl group.

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